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United States Patent 5,347,159. Said application 07/765,928 in turn was a continuation-in-part of United States Patent Application 07/673,020, filed March 21, 1991, now United States Patent 5,148,265 and said Application 07/765,928 was a continuation-in-part of United States Patent Application 07/586,758, filed September 24, 1990, now United States Patent 5,148,266. Said United States Patent Application 08/030,194 is also a continuation-in-part of said Applications 07/586,758 and 07/673,020.--

Page 1, line 9, delete "TECHNICAL FIELD" and insert --BACKGROUND OF THE INVENTION--.

Page 6, line 9, change "sulder" to -- solder --.

Page 12, line 24, change "thermolcompression" to -- thermocompression --.

Page 18, line 13, insert the following:

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Each of figures 31, 32 and 33 is a diagrammatic, perspective view depicting further processes according to the invention.

Page 30, line 32, delete "Chips" and substitute therefor --As illustrated in Fig. 31, chips 928--; same line after "wafer" insert --930--.

Line 35, after "interposers" insert --924--;

Line 36, after "wafer" insert --930--;

Line 38, after "chip" insert --928--;

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Page 31, line 11, after "Alternatively," insert --as illustrated in Figure 32--; same line after "wafer" insert

--950--;

Line 12, after "sheet" insert --952--;

Line 13, change "interposers." to read --interposers 954.--;

Line 16, after "wafer" insert --950--; same line after "sheet" insert --952--;

Line 21, after "sheet" insert --960--;